

### **Abstract Of The Disclosure**

Wire bondable connectors assembly 10 is provided, including a lead element 12 have a lead portion 14 and a carrier strip portion 16, a first coining area 20 and a second coining area 22 formed in the lead element 12, and a connector housing 18 molded to the lead portion 14, including a fence element 24 surrounding the first coining area 20. In this fashion, the carrier strip portion 16 may be separated from the lead portion 14 in the location of the second coining area 22 while leaving the lead portion 14 secure within the connector housing 18.

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